

WE CLAIM:

1. A packaged integrated circuit, comprising:

a die having a surface and corners separated by edges, said die
5 surface including depressions; and
 mold compound covering said die surface and filling said depressions.

2. The packaged integrated circuit of Claim 1, wherein said die comprises bond pads, and further wherein said depressions comprise slots in said bond pads.

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3. The packaged integrated circuit of Claim 1, wherein said depressions comprise trenches at the surface of said die in a dielectric layer.

4. The packaged integrated circuit of Claim 3, wherein said trenches are at said
15 corners of said die.

5. The packaged integrated circuit of Claim 4, wherein said trenches are along
said edges of said die.

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6. The packaged integrated circuit of Claim 1, wherein said surface of said die comprises step-like projections, and further wherein said die surface and said projections are covered with a passivating dielectric, wherein said dielectric covering said step-like projections has sloped edges.

7. A packaged integrated circuit, comprising:

a die comprising a stack of alternating patterned metal and dielectric

layers;

5 a trench in said stack through at least one of said dielectric layers; and
mold compound covering said die and filling said trench.

8. The packaged integrated circuit of Claim 7, wherein said stack includes a

highest layer of patterned metal and a next-highest layer of patterned metal

10 separated by an inter-level dielectric layer, and further wherein said trench is
formed in said interlevel dielectric layer.

9. The packaged integrated circuit of Claim 8, further comprising a dummy pad

formed in said next-highest layer of patterned metal, wherein said trench is

15 formed in said interlevel dielectric layer over said dummy pad.

10. The packaged integrated circuit of Claim 7, wherein said trench is formed at

a corner of said die.

20 11. The packaged integrated circuit of Claim 7, wherein said trench is formed
along the edges of said die.

12. The packaged integrated circuit of Claim 7, wherein said die includes bond pads, said bond pads including slots.

13. The packaged integrated circuit of Claim 7, wherein said die comprises step-like projections, and further wherein said die and said projections are covered with a passivating dielectric, wherein said dielectric covering said step-like projections has sloped edges.

14. A packaged integrated circuit, comprising:

10 a die including bond pads, wherein each of said bond pads comprise a central bonding region and a peripheral region, said peripheral region comprising at least one slot.

15. The packaged integrated circuit of Claim 14, further comprising a passivating dielectric layer over said die, said passivating dielectric layer conformally covering said bond pad and said slots.

16. The packaged integrated circuit of Claim 14, further comprising mold compound covering said die and filling said slots.

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17. The packaged integrated circuit of Claim 15 further comprising mold compound covering said die and filling said slots.

18. The packaged integrated circuit of Claim 17 further comprising a trench in a surface of said die, wherein said mold compound fills said trench.

19. The packaged integrated circuit of Claim 18, wherein said trench is at a
5 corner of said die.

20. The packaged integrated circuit of Claim 14, wherein said bond pads are covered with a passivating dielectric having sloped edges.